



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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企业微信二维码



企业QQ二维码

Features

- $BV_{CEO} > 45V$
- $BV_{CBO} > 45V$
- $I_C = 3.0A$ High Continuous Current
- $hFE > 400 @ 1A$ and Low Saturation Voltage
- $R_{CE(SAT)} = 125m\Omega @ 2A$ for Low Equivalent On-Resistance
- Very Low-Saturation Voltage

Mechanical Data

- Case: SOT223
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads; Solderable per MIL-STD-202, Method 208 Ⓓ
- Weight: 0.112 grams (Approximate)

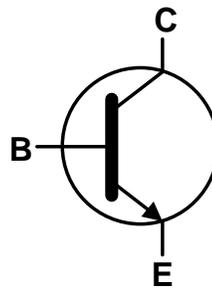
Applications

- Darlington Replacement
- Flash-Gun Convertors and Battery-Powered Circuits
- Siren Drivers, DC-DC Converters

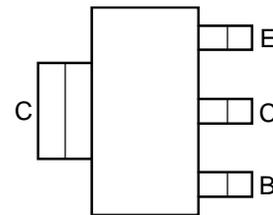
SOT223 (Type DN)



Top View



Device Symbol



Top View
Pin-Out

Absolute Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	45	V
Collector-Emitter Voltage	V_{CEO}	45	V
Emitter-Base Voltage	V_{EBO}	7	V
Continuous Collector Current	I_C	3	A
Peak Pulse Current	I_{CM}	6	A

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

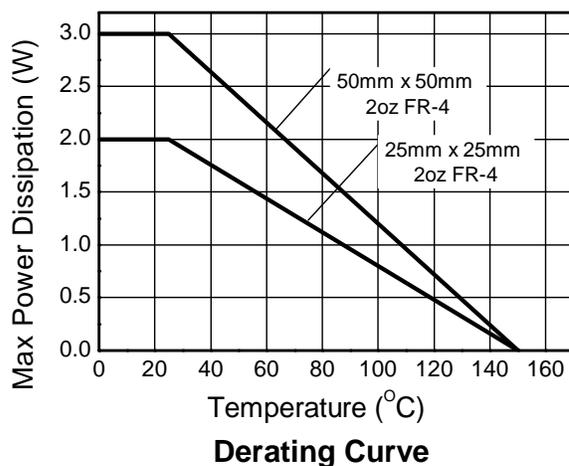
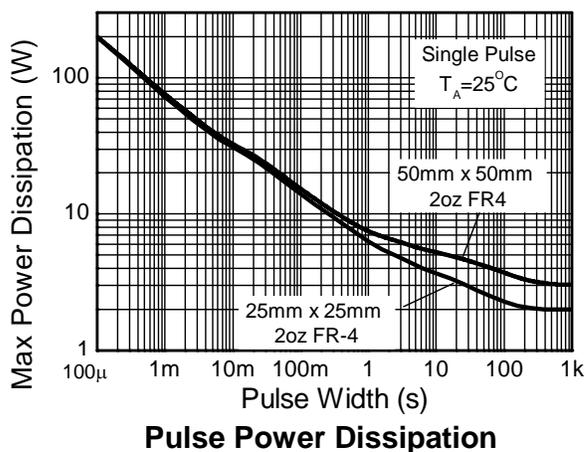
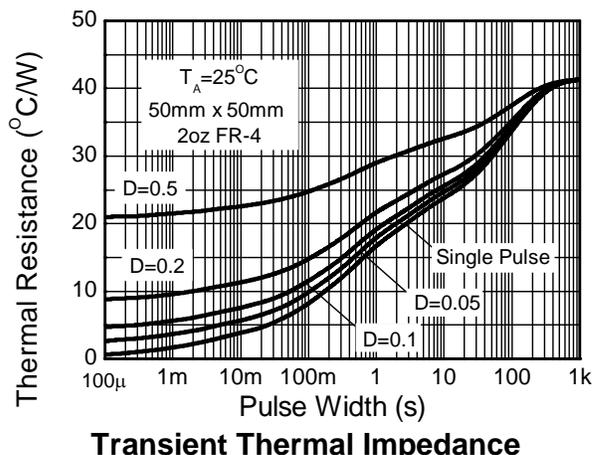
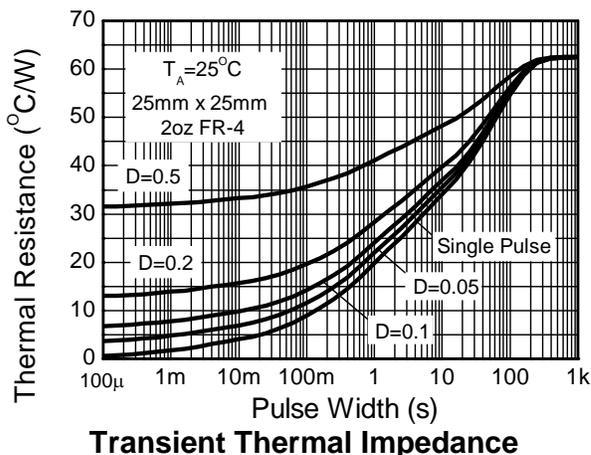
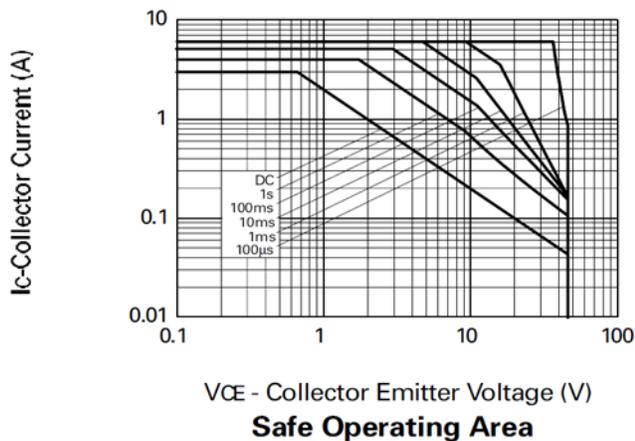
Characteristic	Symbol	Value	Unit
Power Dissipation	P_D	(Note 6)	3.0
		(Note 7)	2.0
		(Note 8)	1.6
		(Note 9)	1.2
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	(Note 6)	41.7
		(Note 7)	62.5
		(Note 8)	78.1
		(Note 9)	104
Thermal Resistance Junction to Lead	$R_{\theta JL}$	12.9	
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

ESD Ratings (Note 11)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
6. For a device mounted with the collector lead on 50mm x 50mm 2oz copper that is on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.
 7. Same as Note 6, except the device is mounted on 25mm x 25mm 2oz copper.
 8. Same as Note 6, except the device is mounted on 25mm x 25mm 1oz copper.
 9. Same as Note 6, except the device is mounted on minimum recommended pad layout.
 10. Thermal resistance from junction to solder-point (at the end of the collector lead).
 11. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information

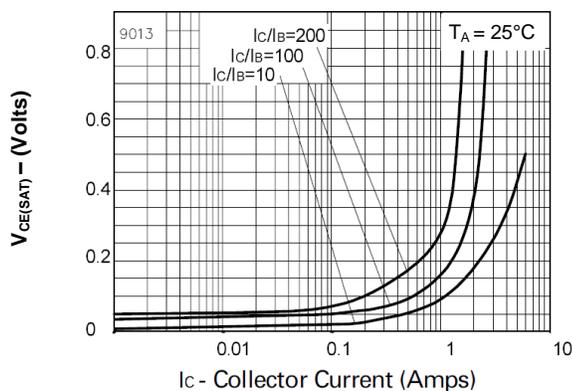


Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

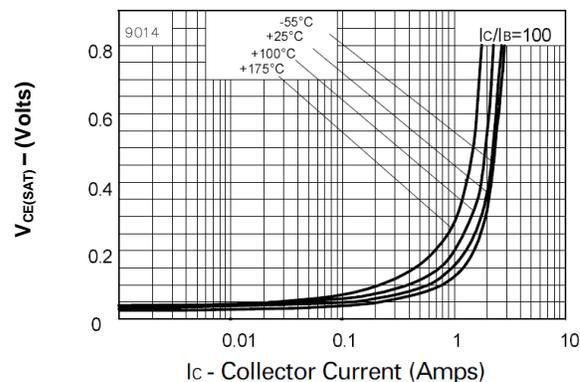
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	45	—	—	V	I _C = 100μA
Collector-Emitter Breakdown Voltage (Note 12)	BV _{CEO}	45	—	—	V	I _C = 10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	7	—	—	V	I _E = 100μA
Collector-Base Cut-Off Current	I _{CBO}	—	—	0.1	μA	V _{CB} = 35V
Emitter Cut-Off Current	I _{EBO}	—	—	0.1	μA	V _{EB} = 4V
DC Current Gain (Note 12)	h _{FE}	500	—	—	—	I _C = 0.1A, V _{CE} = 2V
		400	—	—		I _C = 1A, V _{CE} = 2V
		150	—	—		I _C = 2A, V _{CE} = 2V
		50	—	—		I _C = 3A, V _{CE} = 2V
Collector-Emitter Saturation Voltage (Note 12)	V _{CE(SAT)}	—	—	0.10	V	I _C = 0.1A, I _B = 0.5mA
		—	—	0.50		I _C = 1A, I _B = 5mA
Base-Emitter Saturation Voltage (Note 12)	V _{BE(SAT)}	—	—	0.9	V	I _C = 1A, I _B = 10mA
Base-Emitter Turn-On Voltage (Note 12)	V _{BE(ON)}	—	—	0.9	V	I _C = 1A, V _{CE} = 2V
Input Capacitance	C _{ibo}	—	200	—	pF	V _{EB} = 0.5V, f = 1MHz
Output Capacitance	C _{obo}	—	16	—	pF	V _{CB} = 10V, f = 1MHz
Current Gain-Bandwidth Product	f _T	150	—	—	MHz	V _{CE} = 5V, I _C = 50mA, f=50MHz
Turn-On Time	t _{ON}	—	33	—	ns	V _{CC} = 10V, I _C = 500mA I _{B1} = -I _{B2} = 50mA
Turn-Off Time	t _{OFF}	—	1,300	—	ns	

Note: 12. Measured under pulsed conditions. Pulse width ≤ 300 μs. Duty cycle ≤ 2%.

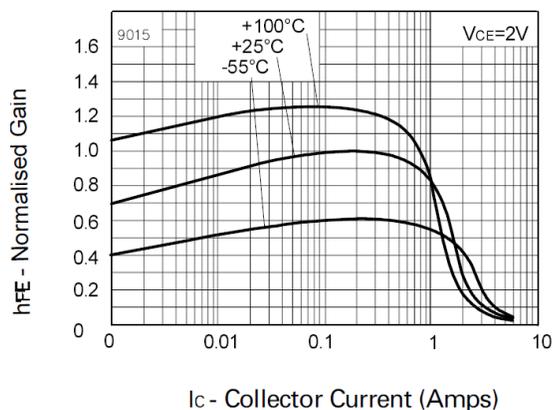
Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)



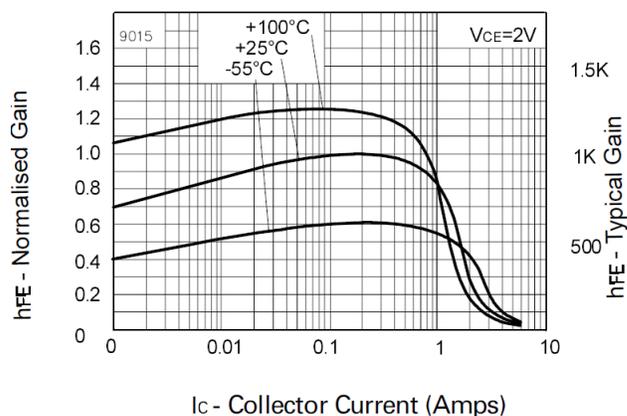
$V_{CE(SAT)} \text{ v } I_C$



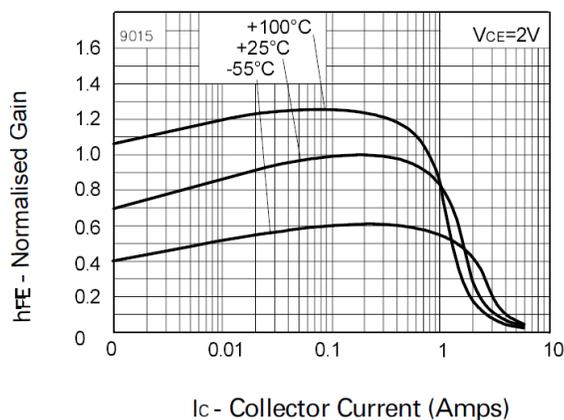
$V_{CE(SAT)} \text{ v } I_C$



$h_{FE} \text{ v } I_C$



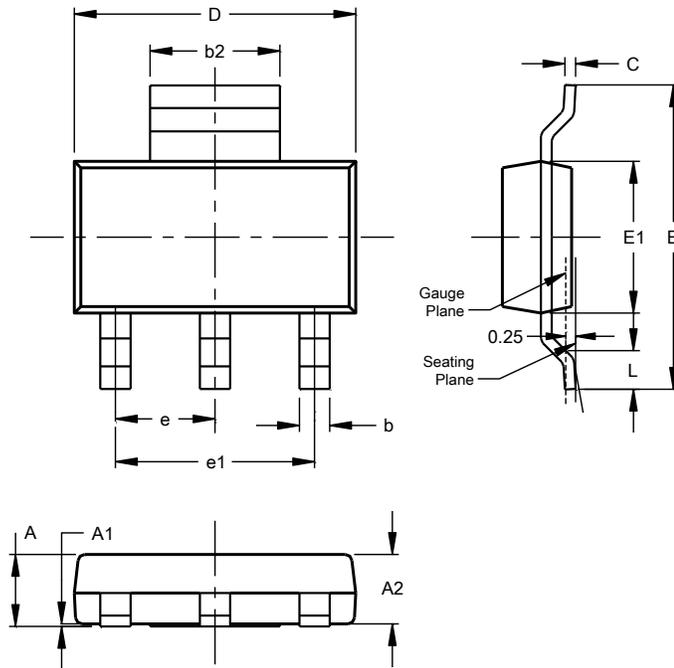
$h_{FE} \text{ v } I_C$



$h_{FE} \text{ v } I_C$

Package Outline Dimensions

SOT223 (Type DN)

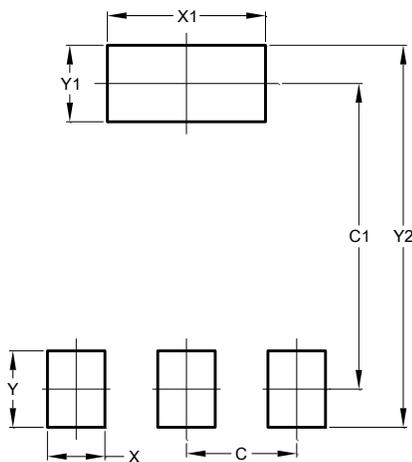


SOT223 (Type DN)			
Dim	Min	Max	Typ
A	--	1.70	--
A1	0.01	0.15	--
A2	1.50	1.68	1.60
b	0.60	0.80	0.70
b2	2.90	3.10	--
c	0.20	0.32	--
D	6.30	6.70	--
E	6.70	7.30	--
E1	3.30	3.70	--
e	--	--	2.30
e1	--	--	4.60
L	0.85	--	--

All Dimensions in mm

Suggested Pad Layout

SOT223 (Type DN)



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00